









B1D10065KF

650V ▲ 10A ▲ SiC SCHOTTKY DIODE

SILICON CARBIDE SIC SCHOTTKY DIODE ▲ THT type

Excellent surge capability
Easy paralleling due to positive V_F temperature coefficient

Temperature independent switching

Low forward voltage

TO-220F-2L package ▲ Electrical insulated mounting tab

Item (T _C = 25°C, unless otherwise noted)		Characteristics
Operating Temperature Range	$T_{\rm J}$	-55°C to +175°C
Storage Temperature Range	Ts	-55°C to +175°C
Repetitive Peak Reverse Voltage	V_{RRM}	650V
Continuous Forward Current at T _c = 95°C	I _F	10A
Total Capacitive Charge (T _J = 25°C)	\mathbf{Q}_{c}	29nC
Capacitance Stored Energy (V _R = 400V)	E c	7.5µJ
Diode Forward Voltage (T _J = 175°C, I _F = 10A)	V_{F}	1.75V
Power Dissipation	P _{TOT}	34W

APPLICATIONS

EV Charging	Industrial Inverters	Motors & Drives	Power Factor Correction	Renewable Energy	SMPS	UPS
₹ /•			PFC	*		

PIN DESCRIPTION

Circuit Diagram	Outline • Front View	Pin No.	Description
	1 2	1 2	Cathode Anode

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ABSOLUT MAXIMUM RATINGS ▲ T_C = 25°C, unless otherwise noted

Item	Condition	Symbol		Unit
Repetitive Peak Reverse Voltage		V_{RRM}	650	V
Non-Repetitive Peak Reverse Voltage		V_{RSM}	650	V
Continuous Forward Current	T _C = 25°C	I _F	15	Α
Continuous Forward Current	T _C = 95°C	I _F	10	Α
Non-Repetitive Forward Surge Current	T_C = 25°C, t_p = 10ms, Half Sine Wave	I _{FSM}	75	Α
I ² t Value	$T_C = 25^{\circ}C$, $t_p = 10$ ms	∫i²dt	28.12	A^2s
Power Dissipation	T _C = 25°C	P _{TOT}	34	W
Power Dissipation	T _C = 110°C	P_{TOT}	15	W
Operating Junction Temperature		TJ	-55 to +175	°C
Storage Temperature Range		T_{STG}	-55 to +175	°C
TO-220 Mounting Torque	M3 Screw		0.7	Nm

ELECTRICAL CHARACTERISTICS

Item	Condition	Symbol	Min.	Тур.	Max.	Unit
Static Characteristics						
DC Blocking Voltage	T _J = 25°C	V_{DC}	650			V
Diode Forward Voltage	$I_F = 10A, T_J = 25^{\circ}C$	V_{F}		1.43	1.60	V
Diode Forward Voltage	$I_F = 10A, T_J = 175^{\circ}C$	V_{F}		1.75	2.10	V
Reverse Current	$V_R = 650V$, $T_J = 25$ °C	I_R		5	70	μΑ
Reverse Current	$V_R = 650V, T_J = 175^{\circ}C$	I _R		50	500	μΑ
Item	Condition	Symbol	Min.	Тур.	Max.	Unit
D : 61		_				
Dynamic Characteristics						
Dynamic Characteristics	V _R = 400V, T _J = 25°C					
Total Capacitive Charge	$V_{R} = 400V, T_{J} = 25^{\circ}C$ $Q_{C} = \int_{0}^{V_{R}} C(V) dV$	Qc		29		nC
		Q _c		29 457		nC pF
Total Capacitive Charge	$Q_C = \int_0^{V_R} C(V) dV$					
Total Capacitive Charge Total Capacitance	$Q_C = \int_0^{V_R} C(V) dV$ $V_R = 1V, f = 1MHz, T_J = 25^{\circ}C$	С		457		pF

THERMAL RESISTANCE PERFORMANCE

ltem	Symbol	Min.	Тур.	Max.	Unit
Thermal Resistance, Junction to Case	$R_{\theta,JC}$		4.331		K/W



REFERENCE DATA A TYPICAL PERFORMANCE

Fig. 1 - Typical Forward Characteristics IF vs. VF

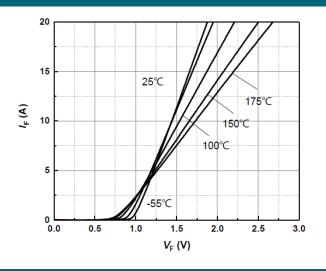


Fig. 2 • Typical Reverse Current I_R as function of Reverse Voltage V_R

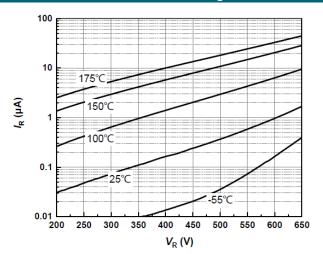


Fig. 3 • Diode Forward Current I_F as function of Case Temperature T_C (D = Duty Cycle)

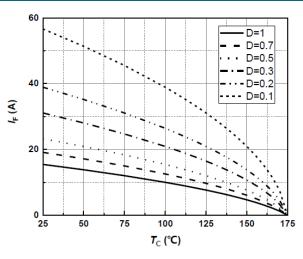


Fig. 4 • Typical Capacitance C as function of Reverse Voltage V_R , $C = f(V_R)$, $T_J = 25^{\circ}C$, f = 1MHz

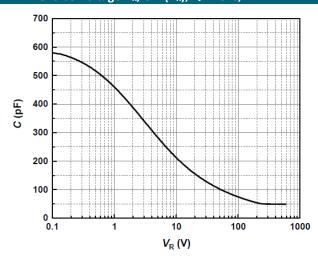


Fig. 5 • Typical Reverse Charge Q_C as function of Reverse Voltage V_R

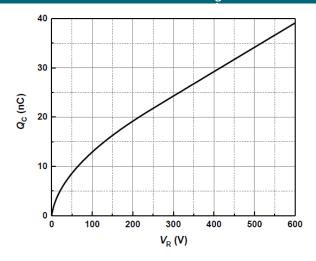
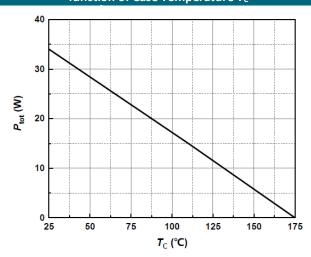


Fig. 6 • Power Dissipation P_{TOT} as function of Case Temperature T_C



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REFERENCE DATA A TYPICAL PERFORMANCE

Fig. 7 - Capacitance Stored Energy

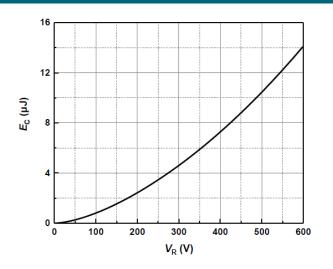
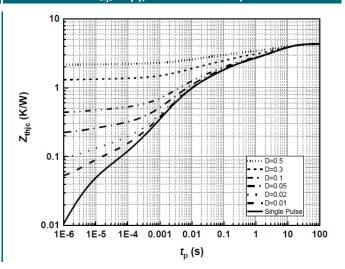
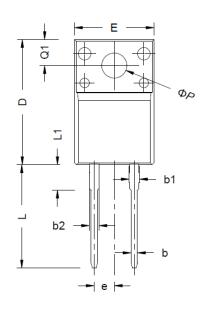


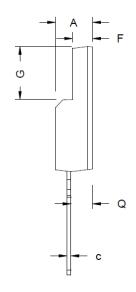
Fig. 8 • Maximum Transient Thermal Impedance, Z_{thjc} = f(t), Parameter: D = t/T

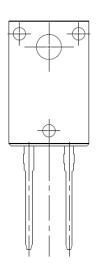




PACKAGE OUTLINE









Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
А	4.60	4.70	4.80
b	0.70	0.80	0.91
b1	1.20	1.30	1.47
b2	1.10	1.20	1.30
С	0.45	0.50	0.63
D	15.80	15.87	15.97
D	15.15	15.45	15.75
е		2.54 BSC	
Е	10.00	10.10	10.30

Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
F	2.44	2.54	2.64
G	6.50	6.70	6.90
L	12.90	13.10	13.30
L	12.70	-	13.70
L1	3.13	3.23	3.33
Q	2.65	2.75	2.85
Q1	3.20	3.30	3.40
ØР	2.08	3.18	3.28

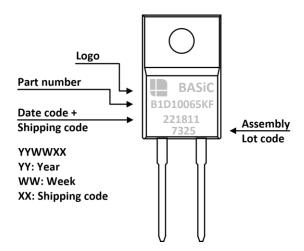
TO-220F-2L package ▲ Epoxy meets UL94-V0

ORDERING INFORMATION

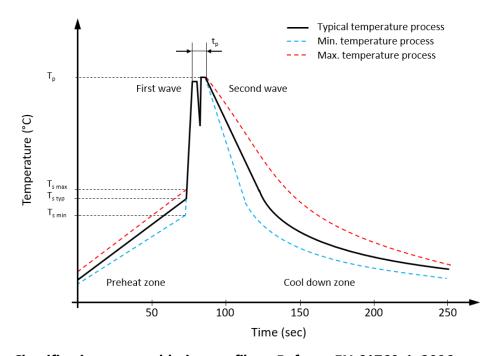
Part Number	Package	Packing	Tube Qty.	Inner Box Qty.	Outer Box Qty.
B1D10065KF	TO-220F-2L	Tube	50pcs	500pcs	5,000pcs



PART MARKING



RECOMMENDED WAVE SOLDERING PROFILE & THT PACKAGE



Classification wave soldering profile ▲ Refer to EN 61760-1: 2006

Profile Features		Value ▲ Sn-Pb Assembly	Value ▲ Pb-free Assembly
Preheat temperature min.	T_{smin}	100 °C	100 °C
Preheat temperature typical	T _{s typ}	120 °C	120 °C
Preheat temperature max.	$T_{s max}$	130 °C	130 °C
Preheat time t_s from T_{smin} to T_{smax}	ts	70 seconds	70 seconds
Peak temperature	T_p	235 °C to 260 °C	245 °C to 260 °C
Time of actual peak temperature	t _p	Max. 10 seconds Max. 5 second each wave	Max. 10 seconds Max. 5 second each wave
Ramp-down date min.		~ 2 °C/second	~ 2 °C/second
Ramp-down rate typical		~ 3.5 °C/second	~ 3.5 °C/second
Ramp-down rate max.		~ 5 °C/second	~ 5 °C/second
Time 25°C to 25°C		4 minutes	4 minutes

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REVISION TABLE

Revision	Date	Status	Notes
001	30/09/2022	Initial release	Initial publication

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